

C1206X473K1RECTU

Aliases (C1206X473K1REC7800) ESD SMD Comm X7R, Ceramic, 0.047 uF, 10%, 100 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 1206, 1.5 mm



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Chip Size 1206 L 3.3mm +/-0.4mm W 1.6mm +/-0.35mm T 1mm +/-0.20mm S 1.5mm MIN	Dimensions	
W 1.6mm +/-0.35mm T 1mm +/-0.20mm	Chip Size	1206
T 1mm +/-0.20mm	L	3.3mm +/-0.4mm
	W	1.6mm +/-0.35mm
S 1.5mm MIN	т	1mm +/-0.20mm
	S	1.5mm MIN
B 0.6mm +/-0.25mm	В	0.6mm +/-0.25mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

General Information	
Series	ESD SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	25 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.047 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	100 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5%1kHz1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	21.2766 GOhms

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